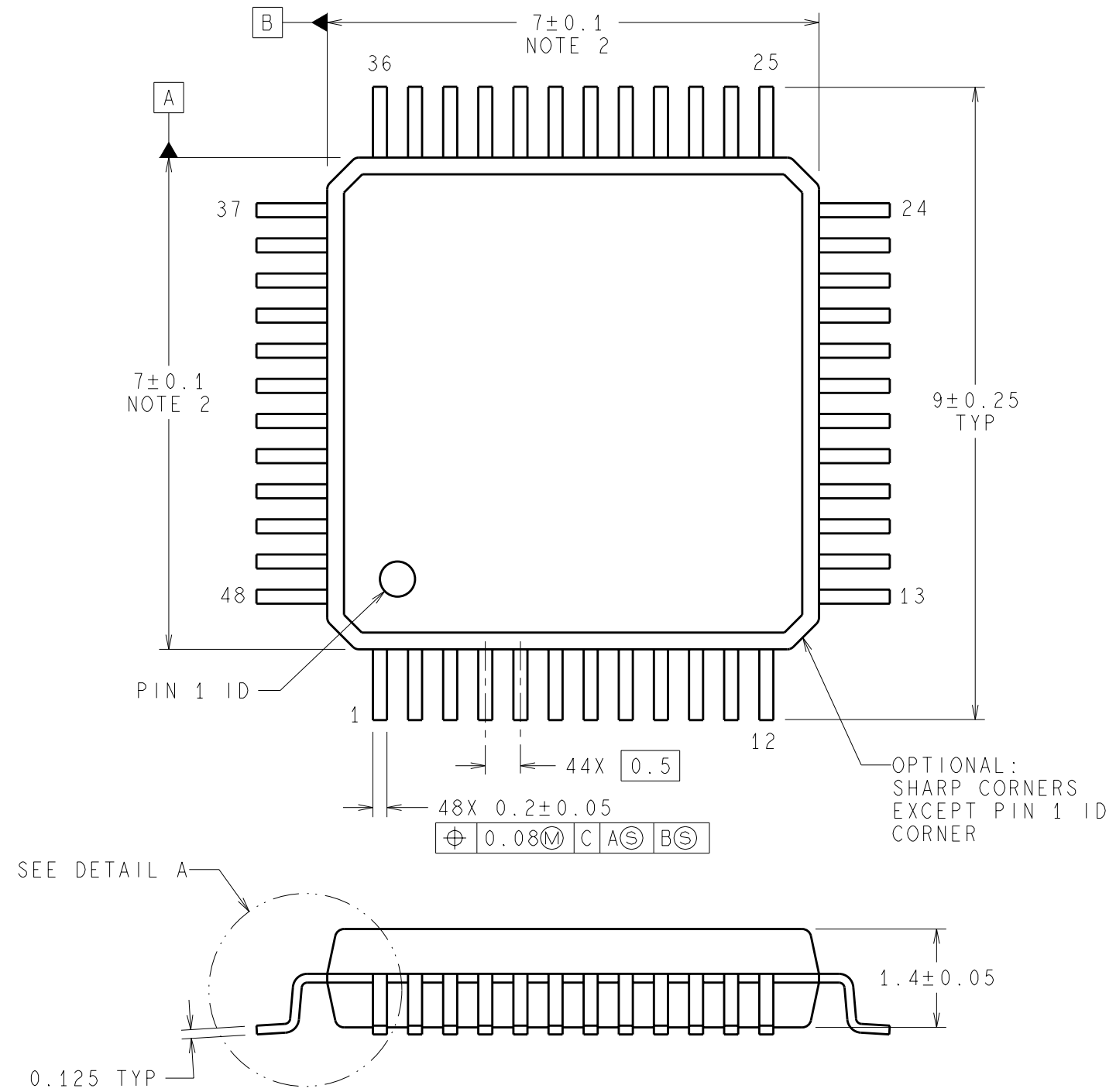
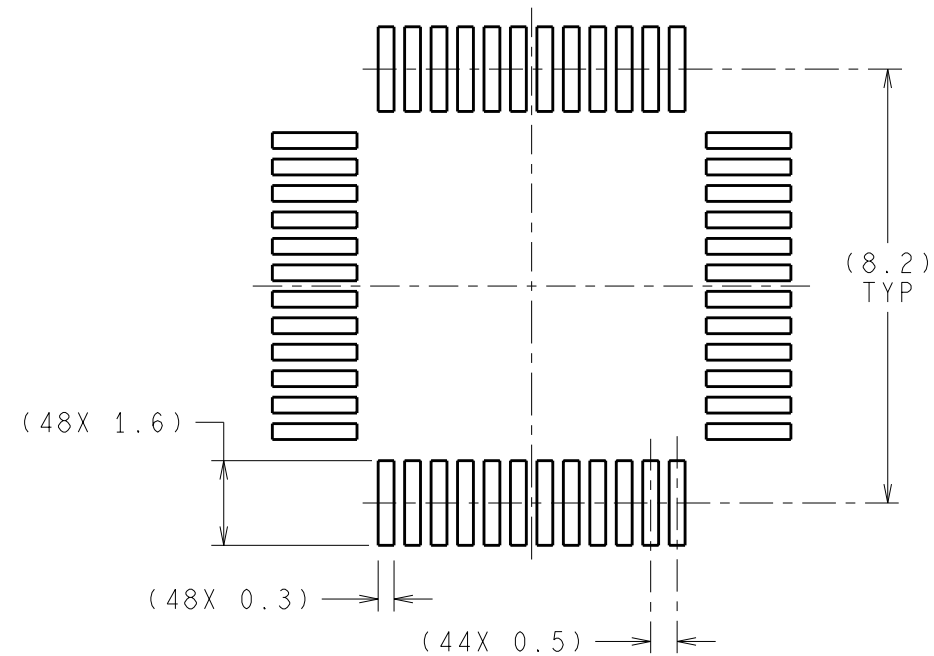


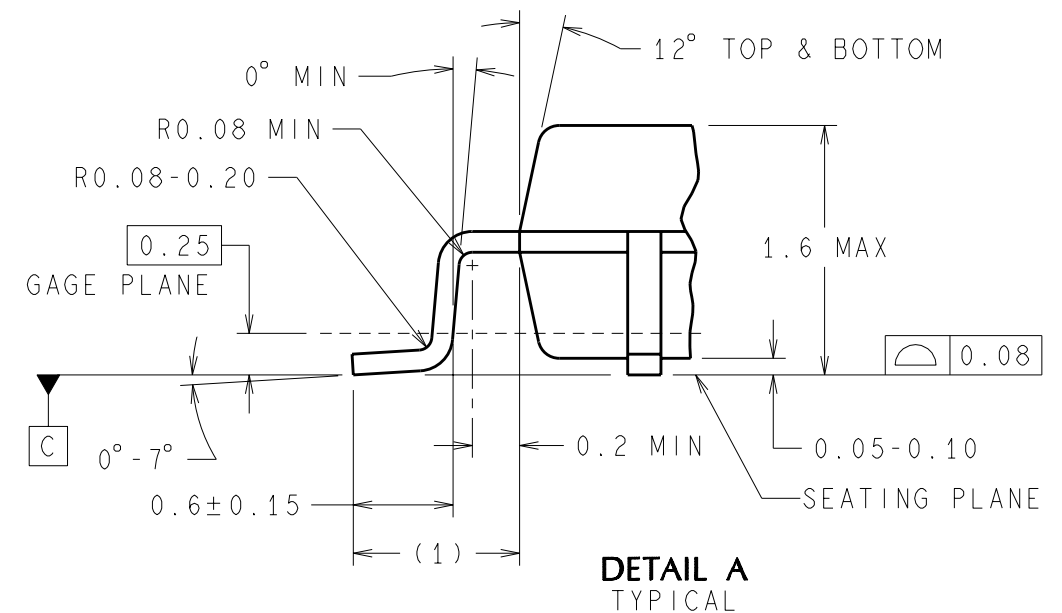
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	TITLE: LQFP WAS POFP; DELETE NOTE 3; UPDATE NEW NOTE 3; ADD GEOMETRIC TOLERANCE; REDRAWN.	12317	12/02/1999	ACS/MS/RW
E	REVISE TITLE: ADD LAND PATTERN; UPDATE DIM'S PER STDS; UPDATE NOTES 1 & 3; CHG DWG FORMAT TO B SIZE	2295	05/23/2007	TL/RW



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY



RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BBC.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	MARTA SUCHY	03/21/1995	
DFTG. CHK.	MARTA SUCHY	05/23/2007	
ENGR. CHK.	RANDALL WALBERG	05/23/2007	
LQFP, 7x7x1.4mm, 48 LEAD, 0.5mm PITCH			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
 MM	NTS	B	(SC)MKT-VBH48A
FORMERLY: N/A			REV E
			SHEET 1 of 1